

New Product Introduction August 2026



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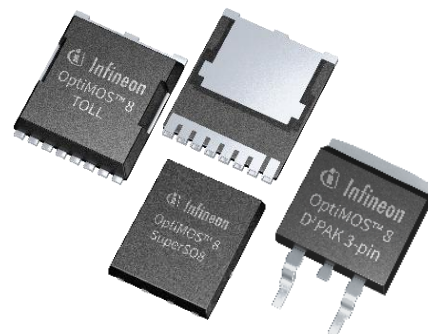
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OptiMOS™ 8 power MOSFET 100 V for motor control and battery protection applications

The new OptiMOS™ 8 power MOSFET 100 V technology is designed to address various motor control and battery protection applications with the need for lowest conduction losses. With industry's lowest $R_{DS(on)}$ and excellent switching behavior, OptiMOS™ 8 100 V enables unmatched power density and system cost savings compared to its predecessor OptiMOS™ 5, all while maintaining next level capabilities and an outstanding price to performance ratio.



Features

- > N-channel, normal level
- > Very low on-resistance $R_{DS(on)}$
- > High I_D current rating
- > Tight $V_{GS(th)}$ spread
- > Soft body diode recovery and low Q_{rr}
- > 100% avalanche tested
- > Pb-free lead plating; RoHS compliant
- > Halogen-free according to IEC 61249-2-21
- > MSL 1 classified according to J-STD-020

Benefits

- > Lowest conduction losses through very low on-resistance $R_{DS(on)}$, resulting in higher peak and steady-state current capability
- > Improved current sharing due to tight $V_{GS(th)}$ spread
- > Excellent EMI behavior due to soft body diode
- > Ease of use

Competitive advantage

- > Price/performance optimized
- > Efficient power handling
- > Power density
- > High reliability

Target applications

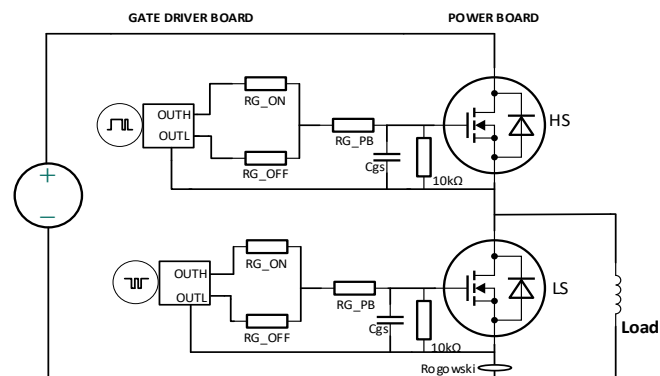
- > Drives
- > Battery management
- > Server
- > Telecom

Product collaterals/online support

[Product family page](#)

Block diagram

48 V servo drive



Product overview incl. datasheet link

OPN	SP Number	Package
ISC019N10NM8SCATMA1	SP006181056	PG-WSO8-8
IPT014N10NM8ATMA1	SP006114977	PG-HSOF-8
ISC040N10NM8ATMA1	SP006114880	PG-TDSO8-8
IPB013N10NM8ATMA1	SP006114960	PG-TO263-3
IPT018N10NM8ATMA1	SP006114985	PG-HSOF-8

EasyPACK™ with IGBT5 and CoolSiC™ Schottky diode for solar boost application

The EasyPACK™ 1B is a high-performance power module for solar boost applications, featuring boost topology and equipped with fast-switching 650 V TRENCHSTOP™ IGBT5, 1200 V CoolSiC™ Schottky diode and integrated NTC. This EasyPACK™ 1B delivers a cost-performance solution for high efficiency and reliability for solar systems.



Features

- > Al₂O₃ substrate with low thermal resistance
- > Solder contact technology
- > Fast switching IGBT
- > Integrated NTC temperature sensor
- > Latest chip technologies

Benefits

- > Compact design
- > High integration single module solution
- > Low stray inductance design with high system efficiency
- > Low switching losses
- > Optimized cost performance

Competitive advantage

- > Easy to design products
- > Best cost-performance ratio which leads to reduced system costs
- > Leading-edge chip technology
- > Supporting the growing demand of solar applications

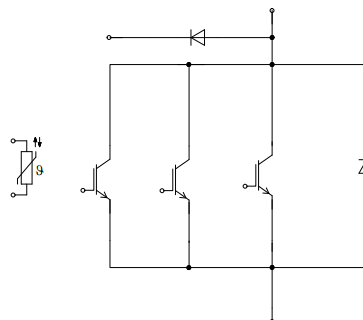
Target applications

- > [Photovoltaic](#)

Product collaterals/online support

[Product page](#)

Block diagram

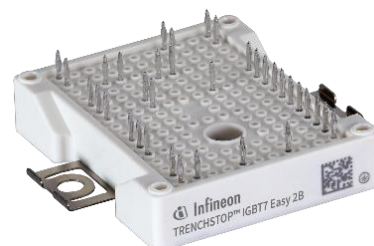


Product overview incl. datasheet link

OPN	SP Number	Package
DF300R07W1H5FB20BPSA1	SP006122774	AG-EASY1B-7011

EasyPACK™ with IGBT5 and EC3 for solar and UPS applications

The EasyPACK™ 2B featuring H6.5 topology is a cost-performance power module solution for solar inverter and UPS applications. Utilizing fast-switching 650 V TRENCHSTOP™ S5, emitter controlled 3 diode, rapid diode and integrated NTC, this EasyPACK™ 2B delivers leading output power, efficiency and reliability for systems.



Features

- > Al₂O₃ substrate with low thermal resistance
- > Solder contact technology
- > H6.5 topology
- > Integrated NTC temperature sensor

Benefits

- > Reduced filter effort benefiting from H6.5 topology
- > High integration single module solution
- > Low stray inductance design with high system efficiency
- > Low switching losses

Competitive advantage

- > Easy to design products
- > Best cost-performance ratio which leads to reduced system costs
- > Enabling reduced filter effort in inverter design with H6.5 topology
- > Supporting the growing demand of solar applications and UPS systems product validation

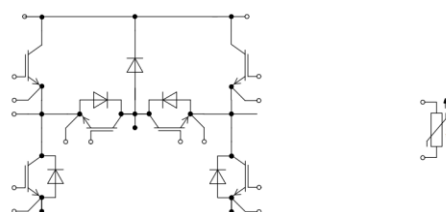
Target applications

- > [Photovoltaic](#)
- > [Uninterruptible power supplies \(UPS\)](#)

Product collaterals/online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
F43L100R07W2S5B40BPSA1	SP006140533	AG-EASY2B-7011

EiceDRIVER™ 2EDL6014AC-G2D - 120 V, junction-isolated, dual channel floating output gate driver IC for IBC AI servers application

The 2EDL6014AC-G2D gate driver is designed to drive dual high-side, dual low-side or half-bridge configurations of Si MOSFETs. It offers two completely floating output gate drivers, especially useful for switched-capacitor and multilevel topologies. The floating high-side drivers are capable of driving a high-side MOSFET operating up to 120 V voltage. It is available in WQFN-11 pins 2.2 mm x 2.2 mm package.



Features

- > Junction isolated dual-channel floating output driver
- > Strong 4 A source and 6 A sink current
- > Configurable driving current on OUTA
- > Package: QFN-11 2.2x2.2 mm w/exposed pad
- > Low RthJC_B
- > 4 V to 16 V driving capability

Benefits

- > Support wide range of power topologies
- > Compact and thermally capable solution
- > Suitable for high power applications
- > Flexible for many customer requirements

Competitive advantage

- > Driver optimized for IBC: in 2.2x2.2 packages allows high density designs
- > Safe system startup thanks to the current starving capability
- > LL FET compatible thanks to wide supply range
- > High efficiency thanks to reduced propagation delay
- > Low thermal impedance thanks to exposed pad
- > Platform driver – can drive dual-high side, dual-low side and half-bridge

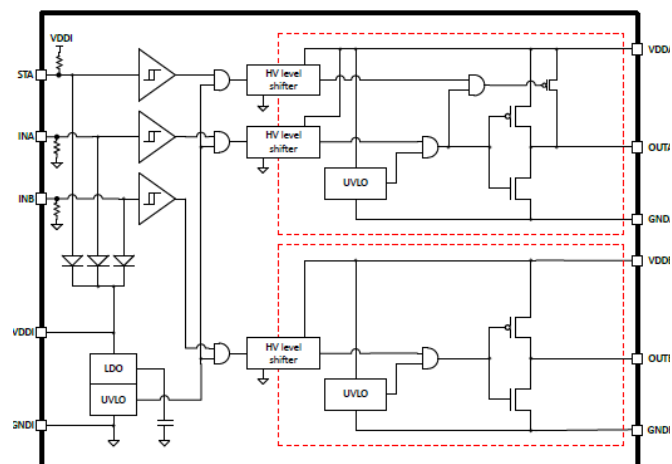
Target applications

- > [Intermediate Bus Converter \(IBC\)](#)
- > [DC-DC power conversion for telecommunications infrastructure](#)
- > [Industrial & Medical SMPS](#)

Product collaterals/online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
2EDL6014ACG2DXTMA1	SP006138793	PG-WQFN-11

EiceDRIVER™ 2EDL900G3 - 120 V dual-channel common footprint gate driver for IBC AI servers application

The 2EDL900G3 gate driver is designed to drive dual high-side, dual low-side or half-bridge configurations of Si MOSFETs. It offers two completely floating output gate drivers, especially useful for switched-capacitor and multilevel topologies. The driver provides 5 configurable input modes and an integrated current sense amplifier with a common input voltage up to 35 V. It is available in 16 pins 3 mm x 3 mm package.



Features

- > Junction isolated dual-channel floating output driver
- > 4 A source/6 A sink output current capability
- > Integrated bootstrap diode
- > 120 V absolute maximum voltage on HB and LB supplies (reference to GND)
- > 4 V to 16 V gate driver supply voltage
- > 15 ns typical propagation delay
- > Integrated current sense amplifier for DCR or shunt based current sensing

Benefits

- > Support wide range of power topologies
- > Compact and thermally capable solution
- > Suitable for high power applications
- > Flexible for many customer requirements

Competitive advantage

- > Dual floating architecture supporting wide range of power topologies
- > Configurable for Hi/Li inputs or single tri-state input for multi-level topologies
- > High efficiency thanks to reduced propagation delay
- > Reduced system BoM with integrated current sensing

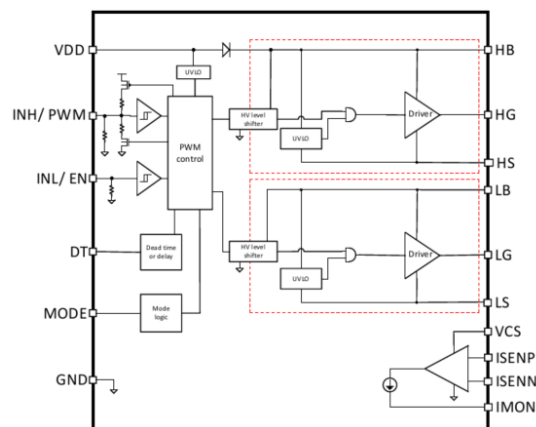
Target applications

- > [Intermediate Bus Converter \(IBC\)](#)
- > [DC-DC power conversion for telecommunications infrastructure](#)
- > [Industrial & Medical SMPS](#)

Product collaterals/online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
2EDL900G3XTMA1	SP006165917	PG-TSNP-16

OPTIREG™ PMIC TLF4D985Q for Infineon's AURIX™ TC4Dx/49x/4Zx microcontrollers

The TLF4D985Q is a high-performance, ASIL-D compliant PMIC designed specifically for Infineon's AURIX™ TC4Dx/49x/4Zx microcontrollers. It supports a wide input voltage range (3.2 V to 52 V) providing up to 50 W pre-regulator power. Featuring the unique capability and integrated safety monitoring, it ensures robust power management for critical automotive safety applications.



Features

- > Seamless integration with AURIX™ TC4x microcontrollers for complete system optimization
- > Best-in-class functional safety concepts, compliance with Grade 0 and ASIL-D safety standards (ISO 26262)
- > Delivers fail-silent and fail-safe state control for critical safety operations
- > Advanced cutoff switch for redundant supply domain isolation in critical fault conditions
- > Handles extended temperature ranges by optimizing power management
- > Optimized for extreme operating conditions, supporting temperatures beyond 150°C
- > Interoperability across hardware and software for shorter development cycles
- > Reliability with support of multi-CPU and multi-threading systems
- > Microcontroller Programming Support (MPS) control via SPI for easier debugging and flexibility
- > Right application fit with dedicated features for compute and control segments

Benefits

- > Maximum safety: fully developed according to ISO 26262 to support ASIL-D automotive applications
- > High efficiency: high-power buck controller providing up to 50 W for demanding processing needs
- > System reliability: integrated technology for enhanced reverse polarity protection
- > Scalability: supports both 12 V and 24 V battery systems (car, truck and CAV)
- > Redundancy: features a cutoff switch for redundant supply domain isolation in case of critical faults
- > Simplified design: tailored specifically as a companion IC for the AURIX™ TC4x family
- > Comprehensive supervision: advanced failure detection with two safe state outputs (SSO1/2)

Competitive advantage

- > Redundant isolation: unlike competitors, it offers a dedicated cutoff switch to isolate supply domains during critical faults
- > Power density: delivers industry-leading 50 W pre-regulator power, specifically optimized for high-end AURIX™ TC4x performance
- > Integrated protection: the unique ReverSafe™ capability simplifies external circuitry for reverse polarity protection

Target applications

- > ADAS domain control, zonal controllers
- > Sensor fusion
- > Connected gateway
- > Drivetrain and transmission applications: inverter, engine management

Product collaterals/online support

[Product page](#)

Product overview incl. datasheet link

OPN	SP Number	Package
TLF4D985QKV03R1XUMA1	SP006105445	PG-LQFP-64

TLE9371xLE CAN FD SIC 8MB with bus wake-up for future network architecture

The TLE9371VLE is a high-speed CAN FD signal-improvement transceiver for automotive and industrial HS-CAN systems, compliant with ISO 11898-2:2024 and supporting data rates up to 8 Mbit/s. It provides strong protection against interference with high ESD robustness and low electromagnetic emissions, often eliminating the need for external protection components. The device also features low-power standby with bus wake-up capability, passive behavior when unpowered and optimized signal symmetry to ensure reliable high-speed communication.



Features

- > SIC reduces ringing at high speed
- > Dedicated low-power modes, like stand-by mode, consume very low quiescent currents while the device is powered up
- > Wake-up pattern detection
- > Compact footprint (3x3 mm)

Benefits

- > Supports growing complexity in new networks with increased number of nodes (sensors, zones, etc.)
- > Higher system efficiency
- > Eliminating false wake-up extends battery life
- > Saves PCB area/smaller footprint

Competitive advantage

- > Bus wake-up for future network architecture
- > Reduced ringing at high speed

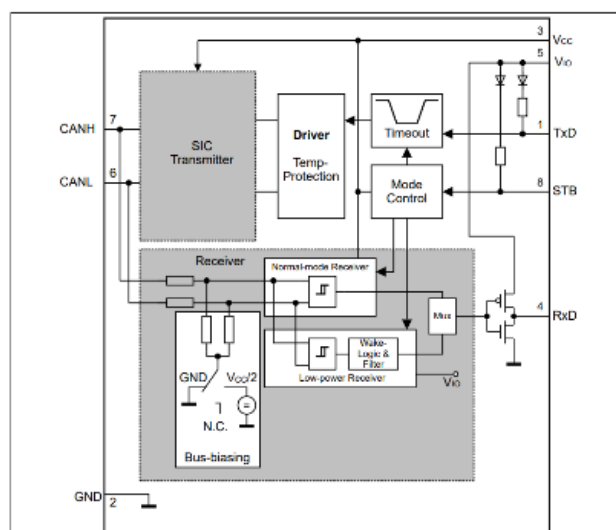
Target applications

- > Engine management
- > Transmission
- > Autonomous driving
- > Lane assist
- > Central gateway

Product collaterals/online support

[Product page](#)

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE9371VLEXUMA1	SP006133629	PG-TSON-8

Evaluation board for GaN Bidirectional Switch (BDS) 650 V G5

The DEMO_AC_ZVS_HVBDS demonstrates the AC soft-switching capability of Infineon's CoolGaN™ Bidirectional Switch 650 V G5 in typical 50/60 Hz AC grid conditions with symmetrical triangular current mode (TCM) operations.



Features

- > Optimized for soft switching
- > Loadless setup for test conditions
- > Simple open loop control

Benefits

- > Commutation driver layout examples
- > No output required, continuous operation
- > Wide current and voltage operating range

Competitive advantage

- > The DEMO_AC_ZVS_HVBDS demonstration board aims to demonstrate the AC soft-switching capability of the BDS in typical 50/60 Hz AC grid conditions with symmetrical triangular current mode (TCM) operations
- > The board features a load-less setup and can test the BDS in a range of voltage, current and switching frequency conditions, all under a simple open-loop control

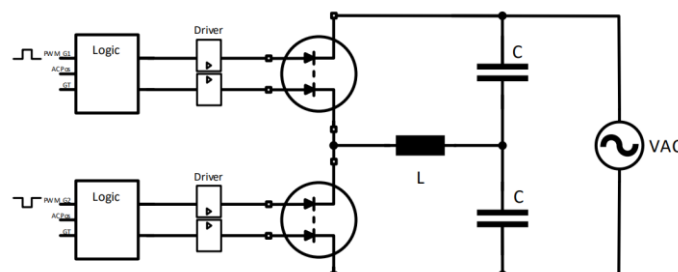
Target applications

- > [1-phase string inverter solutions](#)
- > [3-phase string inverter solutions](#)
- > [Microinverter solutions](#)
- > [Motor control](#)

Product collaterals/online support

[Board page](#)

Block diagram

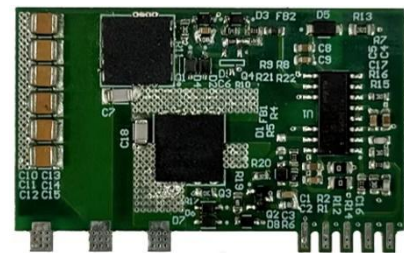


Product overview incl. user guide link

OPN	SP Number	Package
DEMOACZVSHVBDSTOBO1	SP006145922	LG-MADK-1

Half-bridge daughter board with CoolGaN™ Transistor 650 V
G5 in DFN8x8 and bootstrap driver IC with Miller clamp function

KIT_HB_GaN_BT_ML_PFN_A is a half-bridge daughterboard solution for GaN that includes a dual-channel bootstrap gate driver IC (EiceDRIVER™ 2EDB7259Y) and Miller clamp function. On top, this simple plug-in solution facilitates easy replacement of GaN in existing applications.



Features

- > Compact and optimized solution
- > High power and frequency application
- > Easy plug-and-play solution
- > External Miller clamping function

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Higher reliability: Miller clamp prevents false turn-on during high dv/dt switching
- > Compact, cost-effective design: DFN 8x8 package with dual-channel bootstrap driver minimizes PCB area and component count

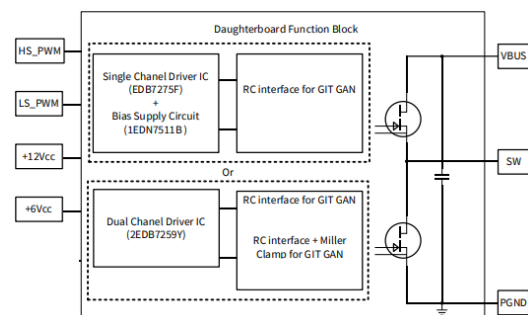
Target applications

- > [Telecommunications infrastructure](#)
- > [AC-DC power conversion for telecommunications infrastructure](#)
- > [Data center power solutions](#)

Product collaterals/online support

[Board page](#)

Block diagram

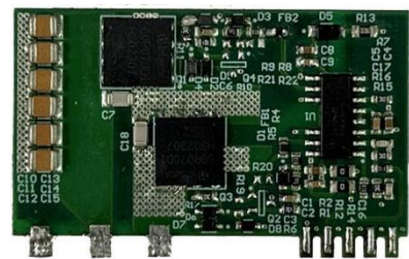


Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANBTMLPFNATOBO1	SP006136446	L-MADK-1

Half-bridge daughter board with CoolGaN™ Transistor 650 V G5 in DFN8x8 and dual-channel bootstrap driver IC

The KIT_HB_GaN_BT_RC_PFN_A is a half-bridge daughter board featuring CoolGaN™ Transistors 650 V G5 in a DFN8x8 package and a dual-channel bootstrap gate driver IC (EiceDRIVER™ 2EDB7259Y). The board allows the driving of CoolGaN™ with bipolar gate-to-source voltages (RC interface circuit).



Features

- > Universal platform with RC circuit
- > Compact and optimized solution
- > High power and frequency application
- > Easy plug-and-play solution

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Optimized switching performance via RC-interface gate drive
- > Lower cost and smaller footprint through bootstrap driver architecture

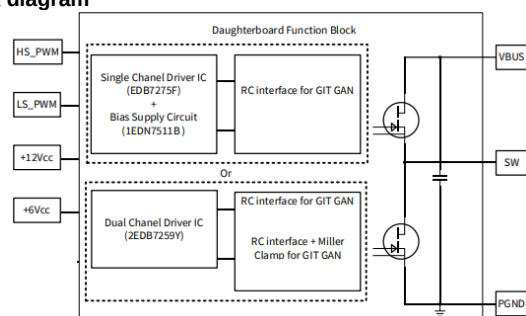
Target applications

- > [Telecommunications infrastructure](#)
- > [AC-DC power conversion for telecommunications infrastructure](#)

Product collaterals/online support

[Board page](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANBTRCPFNATOBO1	SP006136437	L-MADK-1

Half-bridge daughter board with CoolGaN™ Transistor
650 V G5 in TOLL and bootstrap driver IC

The KIT_HB_GaN_BT_RC_TLL_A is a half-bridge daughter board featuring CoolGaN™ Transistors 650 V G5 in a TOLL package and a dual-channel bootstrap gate driver IC (EiceDRIVER™ 2EDB7259Y). The board allows the driving of CoolGaN™ with bipolar gate-to-source voltages (RC interface circuit).



Features

- > Universal platform with RC circuit
- > Compact and optimized solution
- > High power and frequency application
- > Easy plug-and-play solution

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Optimized GaN switching with RC-interface gate drive
- > Reduced BOM and footprint via bootstrap driver architecture

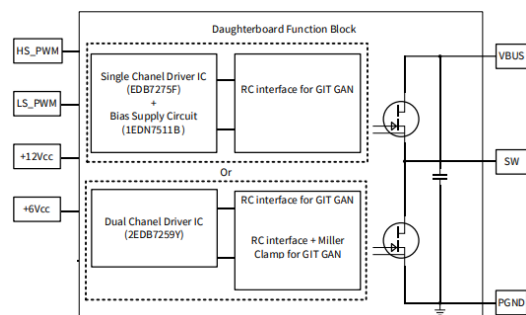
Target applications

- > [Telecommunications infrastructure](#)
- > [AC-DC power conversion for telecommunications infrastructure](#)

Product collaterals/online support

[Board page](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANBTRCTLLATOBO1	SP006136408	L-MADK-1

Half-bridge daughter board with CoolGaN™ Transistor 650 V G5 in TOLL and bootstrap driver IC with Miller clamp function

KIT_HB_GaN_BT_ML_TLL_A is a half-bridge daughterboard solution for GaN that includes a dual-channel bootstrap gate driver IC (EiceDRIVER™ 2EDB7259Y) and Miller clamp function. The board allows the driving of CoolGaN™ Transistors.



Features

- > Compact and optimized solution
- > High power and frequency application
- > Easy plug-and-play solution
- > External Miller clamping function

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Higher switching robustness: Miller clamp suppresses false turn-on
- > Lower system cost and complexity: bootstrap driver reduces component count and PCB area

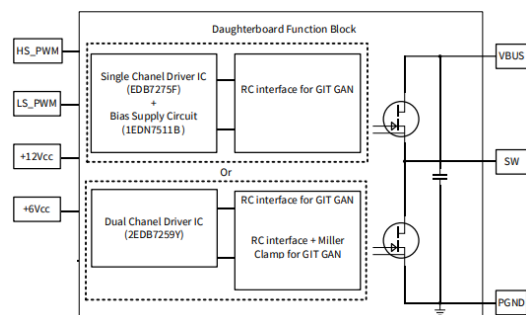
Target applications

- > [Telecommunications infrastructure](#)
- > [AC-DC power conversion for telecommunications infrastructure](#)
- > [Data center power solutions](#)

Product collaterals/online support

[Board page](#)

Block diagram

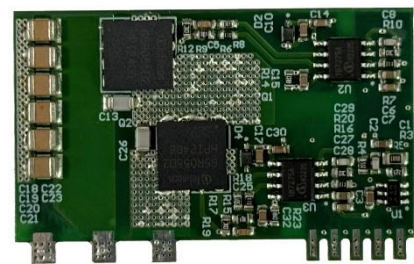


Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANBTMLTLLATOBO1	SP006136440	L-MADK-1

Half-bridge daughter board with ISO aux power and CoolGaN™ Transistor 650 V G5 in DFN8x8 package

The KIT_HB_GAN_ISO_PFN_A is a half-bridge daughter board solution, featuring CoolGaN™ Transistors in DFN8x8, an isolated single-channel gate driver IC (EiceDRIVER™ 1EDB7275F) and a configurable isolated bias supply enabled by a simple single-channel non-isolated gate driver IC (EiceDRIVER™ 1EDN7511B). It is an easy plug-in solution.



Features

- > Universal platform with ISO power supply
- > Compact and optimized solution
- > High power and frequency application
- > Convenient plug-and-play solution

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Stable isolated gate drive with dedicated auxiliary bias supply
- > Reliable switching performance via bipolar RC-interface gate drive

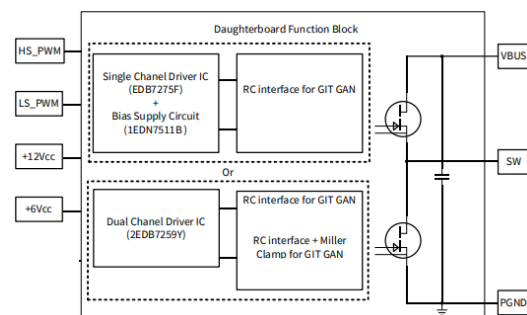
Target applications

- > [Telecommunications infrastructure](#)
- > [AC-DC power conversion for telecommunications infrastructure](#)

Product collaterals/online support

[Board page](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANISOPFNATOBO1	SP006136399	L-MADK-1

Half-bridge daughter board with ISO aux power and CoolGaN™ Transistor 650 V G5 in TOLL

The KIT_HB_GaN_ISO_TLL_A is a half-bridge daughter board solution, featuring CoolGaN™ Transistors, an isolated single-channel gate driver IC (EiceDRIVER™ 1EDB7275F) and a configurable isolated bias supply enabled by a simple single-channel non-isolated gate driver IC (EiceDRIVER™ 1EDN7511B). It is an easy plug-in solution.



Features

- > Universal platform with ISO power supply
- > Compact and optimized solution
- > High power and frequency application
- > Convenient plug-and-play solution

Benefits

- > Configurable via jumper wires
- > Minimal layout impact concerns
- > Easy replacement of gate drivers

Competitive advantage

- > Stable isolated gate drive with dedicated auxiliary bias supply
- > Bipolar RC-interface drive for reliable switching

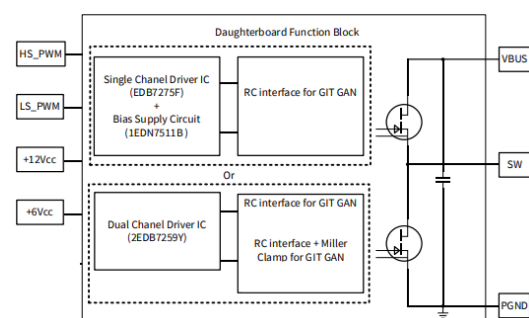
Target applications

- > [AC-DC power conversion for telecommunications infrastructure](#)
- > [Telecommunications infrastructure](#)

Product collaterals/online support

[Board page](#)

Block diagram

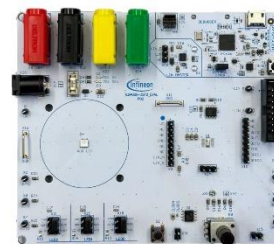


Product overview incl. user guide link

OPN	SP Number	Package
KITHBGANISOTLLATOBO1	SP006136395	L-MADK-1

LITIX™ TLD4020-3STD_EVAL evaluation main board

The TLD4020-3STD_EVAL is the main board of the interior evaluation platform designed to facilitate the development and testing of the LITIX™ TLD4020-3ET device, particularly suited for controlling RGB LEDs. To facilitate the evaluation of the device, a daughter board TLD4020-3DB can be attached to TLD4020-3STD_EVAL. Please note that factory assembly of TLD4020-3STD_EVAL does not include the LITIX™ TLD4020-3ET component.



Features

- > 32-bit Arm® Cortex®-M23 core
- > Three integrated low-side current sinks
- > Reverse polarity and overcurrent-protected input
- > Built-in XMC™ Link debugger
- > GPIO interfaces
- > On-board LIN bootstrap loader connector
- > Test points for main signals probing
- > Pin stripes for TLD4020-3DB board

Benefits

- > Faster development for static interior lighting
- > Software code examples
- > Easy software debug through SWD
- > Well-known industry IDEs (Keil, IAR)

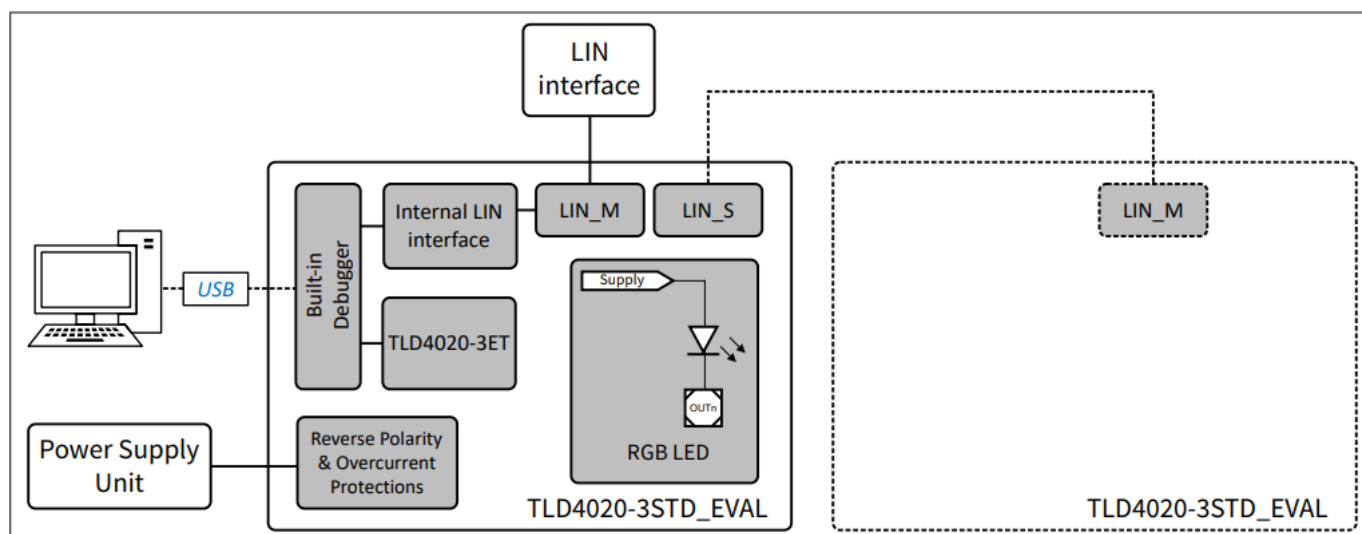
Product collaterals/online support

[Board page](#)

Target applications

- > [Static interior ambient lighting](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
TLD40203STD_EVAL_TOBO1	SP005903912	L-MADK-1

Non-isolated 400 W synchronous buck converter using CoolGaN™ Transistors 80 V

The DEMO_48V12_400W_GAN is a 400 W buck demo board in a half-bridge configuration for 48 V to 12 V.



Features

- > Inductor DCR sensing
- > Configurable controller
- > Optional heatsink for best performance

Benefits

- > Highly efficient
- > Standalone buck demo board
- > Compact design
- > High power density

Competitive advantage

- > 400 W in an ultra-compact form factor enabled by CoolGaN™ technology
- > Combining high efficiency, high-frequency operation, excellent thermal behavior and optimized PCB layout to deliver industry-leading power density for 48 V power architectures

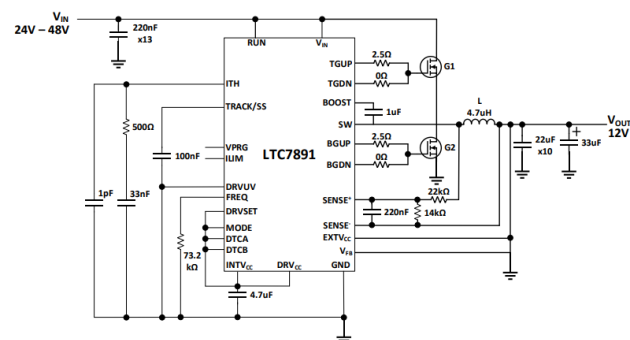
Target applications

- > Medium voltage IBC (48 V)
- > Edge computing

Product collaterals/online support

[Board page](#)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
DEMO48V12400WGANTOBO1	SP006208018	LG-MADK-1

Solar microinverter reference design with GaN bidirectional switch based on cycloconverter topology

REF_500W_CYCLO_BDSGAN is a high efficiency microinverter design based on cycloinverter topology employing bidirectional GaN HEMT devices at the AC switching side. Control is implemented with Infineon's high-performance PSOC™ Control C3 microcontroller with full-featured firmware including AC power flow control, maximum power point tracking (MPPT) and comprehensive protection for safe operation.



Features

- > Grid tied operation
- > Off grid operation mode
- > Real and reactive AC power transfer
- > High efficiency
- > Burst mode for light-load efficiency
- > Displacement power factor 0.8 to 1.0
- > Maximum power point tracking (MPPT)
- > Over voltage and over current protection

Benefits

- > > 97% peak efficiency
- > 96.7% CEC weighted efficiency
- > Minimal thermal losses
- > Safety shutdown with relay disconnect
- > Easy operation with PC based GUI tool

Competitive advantage

- > Based on cycloinverter topology and hence able to operate with soft-switching over a wide operating range
- > CoolGaN™ BDS 650 V G5 offers a significant improvement in system efficiency and power density compared to traditional back-to-back unidirectional solutions

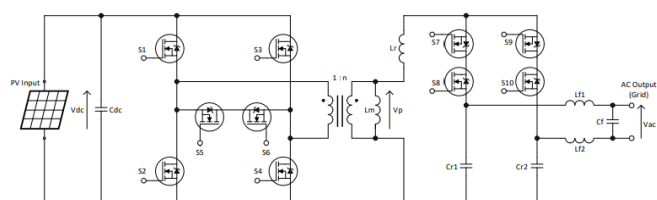
Target applications

- > [Solar microinverters](#)

Product collaterals/online support

[Board page](#)

Block diagram



Product overview incl. application note link

OPN	SP Number	Package
REF500WCYCLOBDSGANTOBO1	SP006173129	LG-MADK-1